

A PROCESS FOR PRODUCING A SEMICONDUCTOR DEVICE

ABSTRACT

The process for producing a semiconductor device according to the invention comprises a pre-sticking/fixing step of pre-sticking/fixing a semiconductor element through an adhesive sheet to an object to which the semiconductor element is to be stuck/ fixed, and a wire bonding step of performing wire bonding without heating step, wherein the shear adhesive force of the adhesive sheet to the object is 0.2 MPa or more at the time of the pre-sticking/fixing. This makes it possible to a semiconductor device producing process wherein a drop in the yield of semiconductor devices is suppressed and steps therein are made simple; an adhesive sheet used in this process; and a semiconductor device obtained by the process.

Fig. 1(c)